

Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxmb7g4f35c5n

Symbol	Description	Minimum	Maximum	Unit
V _{CCPLL_HPS}	HPS PLL analog power supply	–0.50	3.25	V
V _{CC_AUX_SHARED}	HPS auxiliary power supply	–0.50	3.25	V
I _{OUT}	DC output current per pin	–25	40	mA
T _J	Operating junction temperature	–55	125	°C
T _{STG}	Storage temperature (no bias)	–65	150	°C

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in the following table and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle.

For example, a signal that overshoots to 4.00 V can only be at 4.00 V for ~15% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 1.5 years.

Table 1-2: Maximum Allowed Overshoot During Transitions for Arria V Devices

This table lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime.

Table 1-21: Transceiver Clocks Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	MHz
Transceiver Reconfiguration Controller IP (mgmt_clk_clk) clock frequency	—	75	—	125	75	—	125	MHz

Table 1-22: Receiver Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS							
Data rate ⁽²⁸⁾	—	611	—	6553.6	611	—	3125	Mbps
Absolute V _{MAX} for a receiver pin ⁽²⁹⁾	—	—	—	1.2	—	—	1.2	V
Absolute V _{MIN} for a receiver pin	—	−0.4	—	—	−0.4	—	—	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration	—	—	—	2.2	—	—	2.2	V

⁽²⁸⁾ To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.⁽²⁹⁾ The device cannot tolerate prolonged operation at this absolute maximum.

Typical TX V_{OD} Setting for Arria V Transceiver Channels with termination of 100 Ω Table 1-32: Typical TX V_{OD} Setting for Arria V Transceiver Channels with termination of 100 Ω

Symbol	V_{OD} Setting ⁽⁵⁸⁾	V_{OD} Value (mV)	V_{OD} Setting ⁽⁵⁸⁾	V_{OD} Value (mV)
V_{OD} differential peak-to-peak typical	6 ⁽⁵⁹⁾	120	34	680
	7 ⁽⁵⁹⁾	140	35	700
	8 ⁽⁵⁹⁾	160	36	720
	9	180	37	740
	10	200	38	760
	11	220	39	780
	12	240	40	800
	13	260	41	820
	14	280	42	840
	15	300	43	860
	16	320	44	880
	17	340	45	900
	18	360	46	920
	19	380	47	940
	20	400	48	960
	21	420	49	980
	22	440	50	1000
	23	460	51	1020
	24	480	52	1040

⁽⁵⁸⁾ Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.⁽⁵⁹⁾ Only valid for data rates ≤ 5 Gbps.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{IN}	Input clock frequency	–3 speed grade	5	—	800 ⁽⁶¹⁾	MHz
		–4 speed grade	5	—	800 ⁽⁶¹⁾	MHz
		–5 speed grade	5	—	750 ⁽⁶¹⁾	MHz
		–6 speed grade	5	—	625 ⁽⁶¹⁾	MHz
f_{INPFD}	Integer input clock frequency to the phase frequency detector (PFD)	—	5	—	325	MHz
f_{FINPFD}	Fractional input clock frequency to the PFD	—	50	—	160	MHz
$f_{VCO}^{(62)}$	PLL voltage-controlled oscillator (VCO) operating range	–3 speed grade	600	—	1600	MHz
		–4 speed grade	600	—	1600	MHz
		–5 speed grade	600	—	1600	MHz
		–6 speed grade	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	—	40	—	60	%
f_{OUT}	Output frequency for internal global or regional clock	–3 speed grade	—	—	500 ⁽⁶³⁾	MHz
		–4 speed grade	—	—	500 ⁽⁶³⁾	MHz
		–5 speed grade	—	—	500 ⁽⁶³⁾	MHz
		–6 speed grade	—	—	400 ⁽⁶³⁾	MHz

⁽⁶¹⁾ This specification is limited in the Quartus Prime software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

⁽⁶²⁾ The VCO frequency reported by the Quartus Prime software takes into consideration the VCO post-scale counter κ value. Therefore, if the counter κ has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

⁽⁶³⁾ This specification is limited by the lower of the two: I/O f_{MAX} or F_{OUT} of the PLL.

Symbol	Condition	-I3, -C4			-I5, -C5			-C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	SERDES factor $J \geq 8^{(76)(78)}$, LVDS TX with RX DPA	⁽⁷⁷⁾	—	1600	⁽⁷⁷⁾	—	1500	⁽⁷⁷⁾	—	1250	Mbps
	SERDES factor $J = 1$ to 2, Uses DDR Registers	⁽⁷⁷⁾	—	⁽⁷⁹⁾	⁽⁷⁷⁾	—	⁽⁷⁹⁾	⁽⁷⁷⁾	—	⁽⁷⁹⁾	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Network - f_{HSDR} (data rate) ⁽⁸⁰⁾	SERDES factor $J = 4$ to $10^{(81)}$	⁽⁷⁷⁾	—	945	⁽⁷⁷⁾	—	945	⁽⁷⁷⁾	—	945	Mbps
Emulated Differential I/O Standards with One External Output Resistor Network - f_{HSDR} (data rate) ⁽⁸⁰⁾	SERDES factor $J = 4$ to $10^{(81)}$	⁽⁷⁷⁾	—	200	⁽⁷⁷⁾	—	200	⁽⁷⁷⁾	—	200	Mbps
$t_{x \text{ Jitter}}$ - True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	UI

⁽⁷⁸⁾ The V_{CC} and V_{CCP} must be on a separate power layer and a maximum load of 5 pF for chip-to-chip interface.

⁽⁷⁹⁾ The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}), provided you can close the design timing and the signal integrity simulation is clean.

⁽⁸⁰⁾ You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.

⁽⁸¹⁾ When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

DPA Lock Time Specifications

Figure 1-4: Dynamic Phase Alignment (DPA) Lock Time Specifications with DPA PLL Calibration Enabled

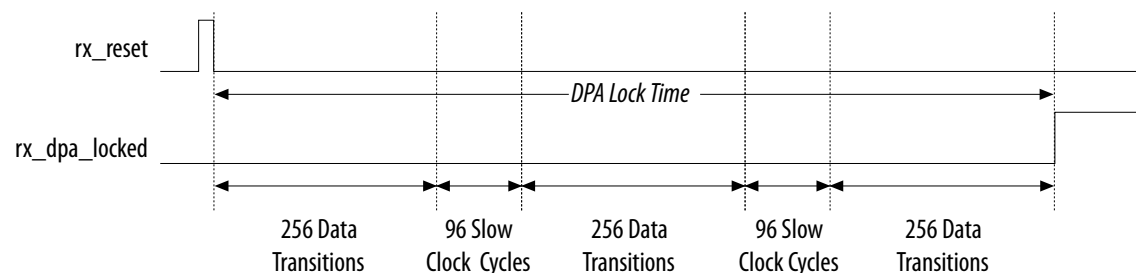


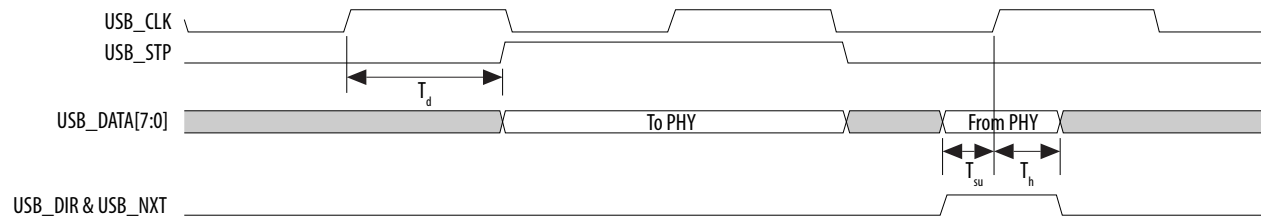
Table 1-41: DPA Lock Time Specifications for Arria V Devices

The specifications are applicable to both commercial and industrial grades. The DPA lock time is for one channel. One data transition is defined as a 0-to-1 or 1-to-0 transition.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁸⁴⁾	Maximum Data Transition
SPI-4	00000000001111111111	2	128	640
Parallel Rapid I/O	00001111	2	128	640
	10010000	4	64	640
Miscellaneous	10101010	8	32	640
	01010101	8	32	640

⁽⁸⁴⁾ This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 1-12: USB Timing Diagram



Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
$T_{duty cycle}$	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	−0.85	—	0.15	ns

Figure 1-13: RGMII TX Timing Diagram

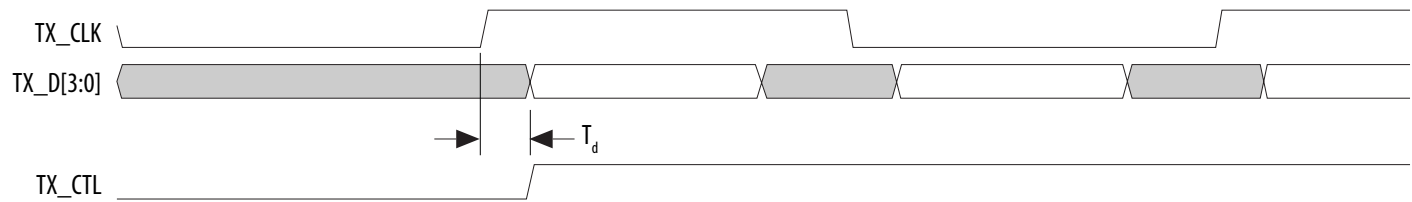
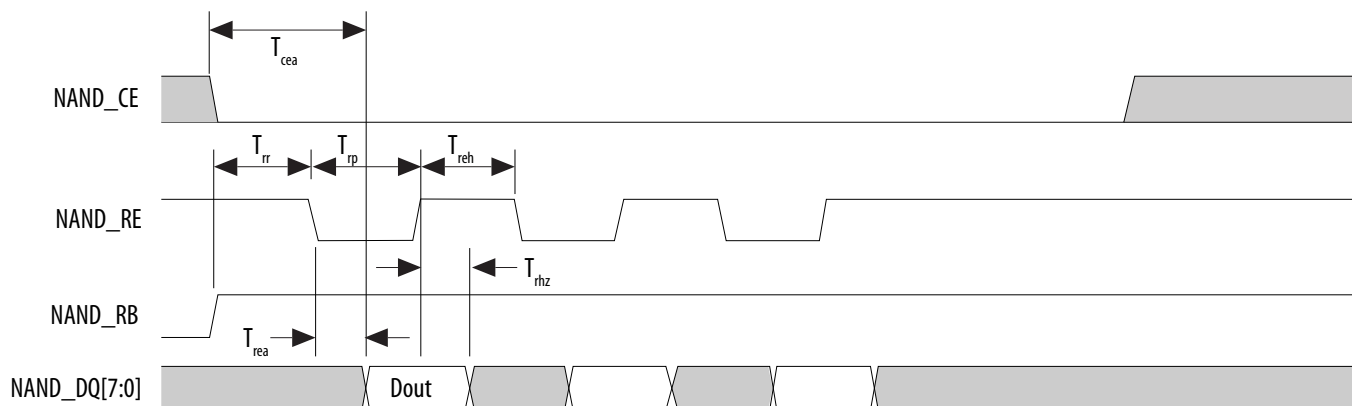


Figure 1-20: NAND Data Read Timing Diagram



ARM Trace Timing Characteristics

Table 1-61: ARM Trace Timing Requirements for Arria V Devices

Most debugging tools have a mechanism to adjust the capture point of trace data.

Description	Min	Max	Unit
CLK clock period	12.5	—	ns
CLK maximum duty cycle	45	55	%
CLK to D0 –D7 output data delay	–1	1	ns

UART Interface

The maximum UART baud rate is 6.25 megasymbols per second.

GPIO Interface

The minimum detectable general-purpose I/O (GPIO) pulse width is 2 μ s. The pulse width is based on a debounce clock frequency of 1 MHz.

Related Information

- [PS Configuration Timing](#) on page 1-81
- [AS Configuration Timing](#)
Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
DCLK frequency in AS configuration scheme	5.3	7.9	12.5	MHz
	10.6	15.7	25.0	MHz
	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽¹⁰³⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽¹⁰⁴⁾	μs

⁽¹⁰³⁾ You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽¹⁰⁴⁾ You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

Term	Definition
JTAG timing specifications	<p>JTAG Timing Specifications</p> <p>The diagram illustrates the timing requirements for JTAG signals. TMS and TDI are high during the first two clock cycles and low during the next two. TCK is a periodic square wave. TDO is high during the first two clock cycles and low during the next two. Various timing parameters are indicated: t_{JCP} (TCK high pulse width), t_{JCH} (TCK high setup time), t_{JCL} (TCK high hold time), t_{JPSU} (TCK high setup time for TDO), t_{JPH} (TCK high hold time for TDO), t_{JPZX} (TDO setup time), t_{JPCO} (TDO output delay), and t_{JPXZ} (TDO output delay).</p>

Date	Version	Changes
December 2015	2015.12.16	<ul style="list-style-type: none">Updated Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Arria V Devices table.<ul style="list-style-type: none">Updated F_{clk}, $T_{duty\ cycle}$, and $T_{dss\ first}$ specifications.Added T_{qspi_clk}, T_{din_start}, and T_{din_end} specifications.Removed $T_{din\ max}$ specifications.Updated the minimum specification for T_{clk} to 16.67 ns and removed the maximum specification in SPI Master Timing Requirements for Arria V Devices table.Updated Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices table.<ul style="list-style-type: none">Updated T_{clk} to $T_{sdmmc_clk_out}$ symbol.Updated $T_{sdmmc_clk_out}$ and T_d specifications.Added T_{sdmmc_clk}, T_{su}, and T_h specifications.Removed $T_{din\ max}$ specifications.Updated the following diagrams:<ul style="list-style-type: none">Quad SPI Flash Timing DiagramSD/MMC Timing DiagramUpdated configuration .rbf sizes for Arria V devices.Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.

Date	Version	Changes
August 2013	3.5	<ul style="list-style-type: none">Removed “Pending silicon characterization” note in Table 29.Updated Table 25.
August 2013	3.4	<ul style="list-style-type: none">Removed Preliminary tags for Table 1, Table 2, Table 3, Table 4, Table 5, Table 6, Table 7, Table 9, Table 12, Table 13, Table 14, Table 15, Table 16, Table 17, Table 18, Table 19, Table 20, Table 21, Table 22, Table 23, Table 24, Table 25, Table 26, Table 27, Table 28, Table 29, Table 30, Table 31, Table 35, Table 36, Table 51, Table 53, Table 54, Table 55, Table 56, Table 57, Table 60, Table 62, and Table 64.Updated Table 1, Table 3, Table 11, Table 19, Table 20, Table 21, Table 22, Table 25, and Table 29.
June 2013	3.3	Updated Table 20, Table 21, Table 25, and Table 38.
May 2013	3.2	<ul style="list-style-type: none">Added Table 37.Updated Figure 8, Figure 9, Figure 20, Figure 22, and Figure 23.Updated Table 1, Table 5, Table 10, Table 13, Table 19, Table 20, Table 21, Table 23, Table 29, Table 39, Table 40, Table 46, Table 56, Table 57, Table 60, and Table 64.Updated industrial junction temperature range for –I3 speed grade in “PLL Specifications” section.
March 2013	3.1	<ul style="list-style-type: none">Added HPS reset information in the “HPS Specifications” section.Added Table 60.Updated Table 1, Table 3, Table 17, Table 20, Table 29, and Table 59.Updated Figure 21.

Symbol	Description	Conditions	Resistance Tolerance		Unit
			C3, I3L	C4, I4	
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 1.2 V	±50	±50	%
50-Ω R _S	Internal series termination without calibration (50-Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50-Ω setting)	V _{CCIO} = 1.2 V	±50	±50	%
100-Ω R _D	Internal differential termination (100-Ω setting)	V _{CCIO} = 2.5 V	±25	±25	%

Figure 2-1: OCT Variation Without Re-Calibration for Arria V GZ Devices

$$R_{OCT} = R_{SCAL} \left(1 + \left(\frac{dR}{dT} \times \Delta T \right) \pm \left(\frac{dR}{dV} \times \Delta V \right) \right)$$

Notes:

1. The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO}.
2. R_{SCAL} is the OCT resistance value at power-up.
3. ΔT is the variation of temperature with respect to the temperature at power-up.
4. ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
5. dR/dT is the percentage change of R_{SCAL} with temperature.
6. dR/dV is the percentage change of R_{SCAL} with voltage.

Table 2-12: OCT Variation after Power-Up Calibration for Arria V GZ Devices

Valid for a V_{CCIO} range of ±5% and a temperature range of 0° to 85°C.

Core Performance Specifications

Clock Tree Specifications

Table 2-33: Clock Tree Performance for Arria V GZ Devices

Symbol	Performance		Unit
	C3, I3L	C4, I4	
Global and Regional Clock	650	580	MHz
Periphery Clock	500	500	MHz

PLL Specifications

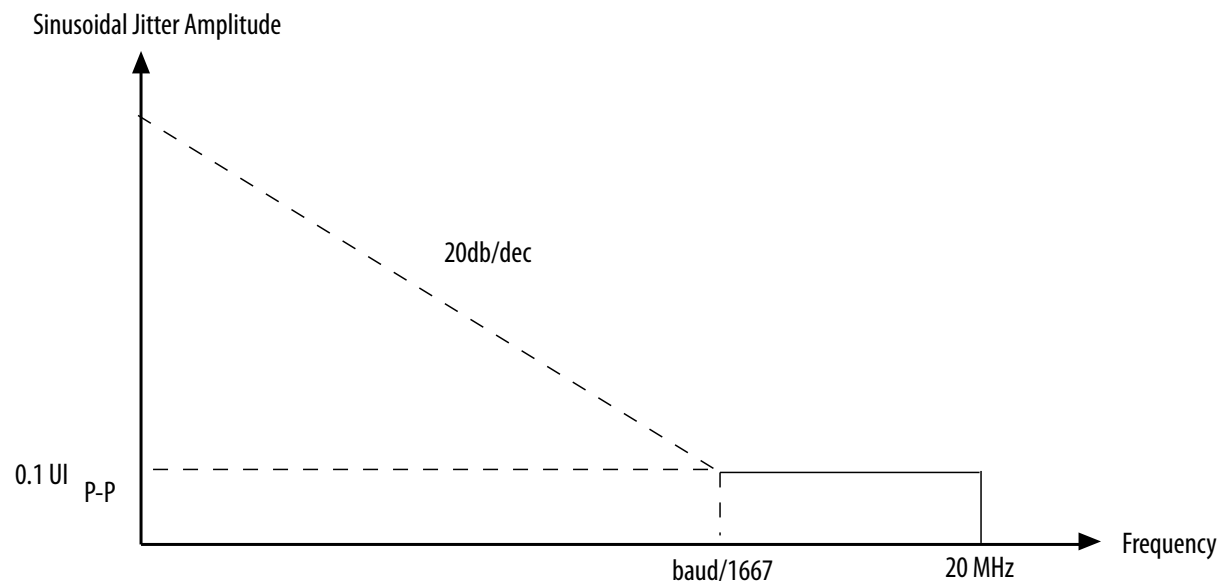
Table 2-34: PLL Specifications for Arria V GZ Devices

Symbol	Parameter	Min	Typ	Max	Unit
$f_{IN}^{(167)}$	Input clock frequency (C3, I3L speed grade)	5	—	800	MHz
	Input clock frequency (C4, I4 speed grade)	5	—	650	MHz
f_{INPFD}	Input frequency to the PFD	5	—	325	MHz
f_{FINPFD}	Fractional Input clock frequency to the PFD	50	—	160	MHz
$f_{VCO}^{(168)}$	PLL VCO operating range (C3, I3L speed grade)	600	—	1600	MHz
	PLL VCO operating range (C4, I4 speed grade)	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%

⁽¹⁶⁷⁾ This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

⁽¹⁶⁸⁾ The VCO frequency reported by the Quartus II software in the **PLL Usage Summary** section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

Figure 2-5: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



Non DPA Mode High-Speed I/O Specifications

Table 2-46: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sampling Window	—	—	—	300	—	—	300	ps

Note: When you enable the decompression or design security feature, the DCLK-to-DATA[] ratio varies for FPP ×8, FPP ×16, and FPP ×32. For the respective DCLK-to-DATA[] ratio, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.

Table 2-56: FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1

Use these timing parameters when the decompression and design security features are disabled.

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μs
t _{STATUS}	nSTATUS low pulse width	268	1,506 ⁽²⁰⁵⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁰⁶⁾	μs
t _{CF2CK} (207)	nCONFIG high to first rising edge on DCLK	1,506	—	μs
t _{ST2CK} ⁽²⁰⁷⁾	nSTATUS high to first rising edge of DCLK	2	—	μs
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{\text{MAX}}$	—	s
t _{CL}	DCLK low time	$0.45 \times 1/f_{\text{MAX}}$	—	s
t _{CLK}	DCLK period	$1/f_{\text{MAX}}$	—	s
f _{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽²⁰⁸⁾	175	437	μs

⁽²⁰⁵⁾ This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽²⁰⁶⁾ This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

⁽²⁰⁷⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	$4 \times \text{maximum DCLK period}$	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ (209)	—	—

Related Information

- [DCLK-to-DATA\[\] Ratio \(r\) for FPP Configuration](#) on page 2-57
- [Configuration, Design Security, and Remote System Upgrades in Arria V Devices](#)

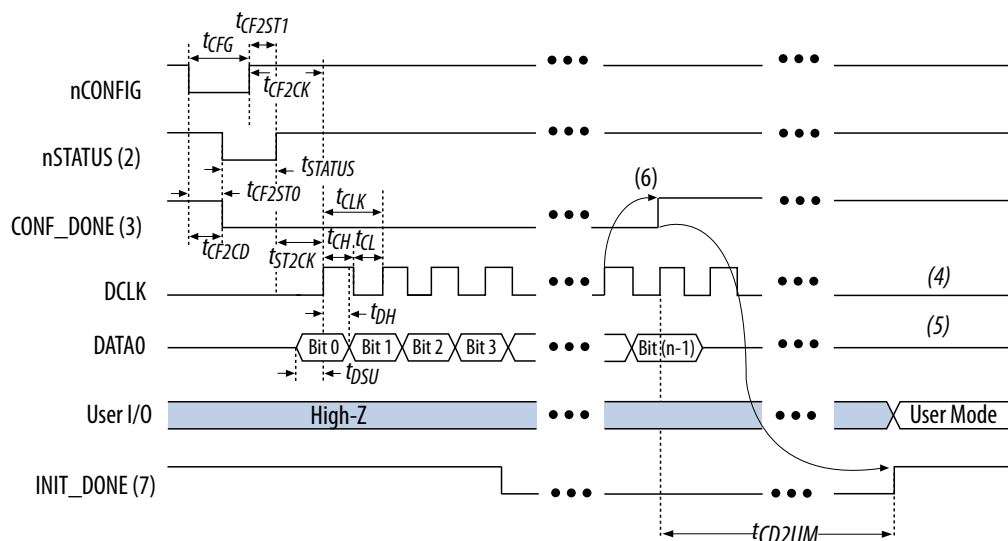
⁽²⁰⁸⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

⁽²⁰⁹⁾ To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

Passive Serial Configuration Timing

Figure 2-10: PS Configuration Timing Waveform

Timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.



Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the Device and Pins Option.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high after the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 2-62: Uncompressed .rbf Sizes for Arria V GZ Devices

Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ⁽²²³⁾
Arria V GZ	E1	137,598,880	562,208
	E3	137,598,880	562,208
	E5	213,798,880	561,760
	E7	213,798,880	561,760

Table 2-63: Minimum Configuration Time Estimation for Arria V GZ Devices

Variant	Member Code	Active Serial ⁽²²⁴⁾			Fast Passive Parallel ⁽²²⁵⁾		
		Width	DCLK (MHz)	Min Config Time (ms)	Width	DCLK (MHz)	Min Config Time (ms)
Arria V GZ	E1	4	100	344	32	100	43
	E3	4	100	344	32	100	43
	E5	4	100	534	32	100	67
	E7	4	100	534	32	100	67

Remote System Upgrades Circuitry Timing Specification

Table 2-64: Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
$t_{RU_nCONFIG}$ ⁽²²⁶⁾	250	—	ns
$t_{RU_nRSTIMER}$ ⁽²²⁷⁾	250	—	ns

⁽²²³⁾ The IOCSR .rbf size is specifically for the Configuration via Protocol (CvP) feature.

⁽²²⁴⁾ DCLK frequency of 100 MHz using external CLKUSR.

⁽²²⁵⁾ Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Term	Definition
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—clock boost factor

Document Revision History

Date	Version	Changes
February 2017	2017.02.10	<ul style="list-style-type: none"> Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1" table. Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1" table. Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices" table. Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Arria V GZ Devices" table. Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices" table.